### SN74LVC02A-Q1 QUADRUPLE 2-INPUT POSITIVE-NOR GATE

SCES465B - JULY 2003 - REVISED MAY 2004

 Qualification in Accordance With AEC-Q100†

- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Inputs Accept Voltages to 5.5 V

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### description/ordering information

The quadruple 2-input positive-NOR gate is designed for 2.7-V to 3.6-V V<sub>CC</sub> operation.

The SN74LVC02A performs the Boolean function  $Y = \overline{A + B}$  or  $Y = \overline{A} \bullet \overline{B}$  in positive logic.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

### ORDERING INFORMATION

TA	PACKAGE <sup>‡</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
4000 1- 40500	SOIC - D	Tape and reel	SN74LVC02AQDRQ1	LVC02AQ	
-40°C to 125°C	TSSOP - PW	Tape and reel	SN74LVC02AQPWRQ1	LC02AQ	

<sup>‡</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

# FUNCTION TABLE (each gate)

INP	UTS	OUTPUT
Α	В	Υ
Н	Χ	L
Х	Н	L
L	L	Н

### logic diagram, each gate (positive logic)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



<sup>†</sup> Contact factory for details. Q100 qualification data available on request.

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 6.5 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 6.5 V
Output voltage range, V <sub>O</sub> (see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{ K }(V_{ C } < 0)$	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through V <sub>CC</sub> or GND	±100 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3): D package	86°C/W
PW package	113°C/W
Storage temperature range, T <sub>sto</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The value of V<sub>CC</sub> is provided in the recommended operating conditions table.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
.,	Operating	Operating	2	3.6	.,
VCC	Supply voltage	Data retention only	1.5		V
VIH	High-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		V
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	V
٧ <sub>I</sub>	Input voltage			5.5	V
VO	Output voltage		0	VCC	V
	LPak lavel androd compart	V <sub>CC</sub> = 2.7 V		-12	4
ЮН	High-level output current	V <sub>CC</sub> = 3 V		-24	mA
1	Laurel autout aumant	$V_{CC} = 2.7 \text{ V}$		12	A
lOL	Low-level output current	V <sub>CC</sub> = 3 V		24	mA
TA	Operating free-air temperature		-40	125	°C

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		vcc	MIN	TYP	MAX	UNIT
	I <sub>OH</sub> = -100 μA	2.7 V to 3.6 V	V <sub>CC</sub> -0.2	2			
.,			2.7 V	2.2			V
VOH	IOH = -12  mA	3 V	2.4				
	$I_{OH} = -24 \text{ mA}$		3 V	2.2			
VOL	I <sub>OL</sub> = 100 μA		2.7 V to 3.6 V			0.2	
	I <sub>OL</sub> = 12 mA	2.7 V			0.4	V	
	I <sub>OL</sub> = 24 mA		3 V			0.55	
IĮ	V <sub>I</sub> = 5.5 V or GND		3.6 V			±5	μΑ
Icc	$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			10	μΑ
ΔICC	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND		2.7 V to 3.6 V			500	μΑ
Ci	$V_I = V_{CC}$ or GND		3.3 V		5		pF

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

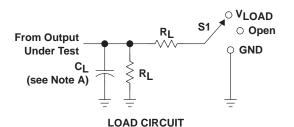
# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	
<sup>t</sup> pd	A or B	Υ		6.5	1	5.5	ns

## operating characteristics, T<sub>A</sub> = 25°C

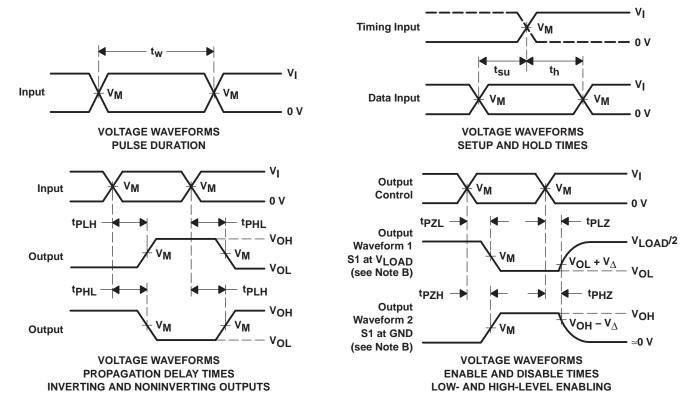
PARAMETER		TECT CONDITIONS	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	LINUT
		TEST CONDITIONS	TYP	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance per gate	f = 10 MHz	8.5	9.5	pF

### PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

V	INPUTS		.,	v			V
VCC	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	VLOAD	СL	$R_L$	$v_{\scriptscriptstyle\Delta}$
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

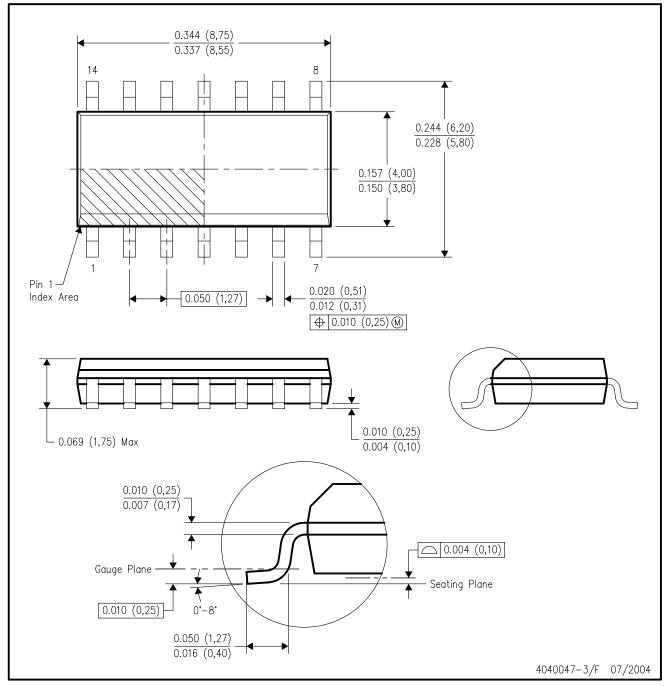
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



# D (R-PDSO-G14)

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

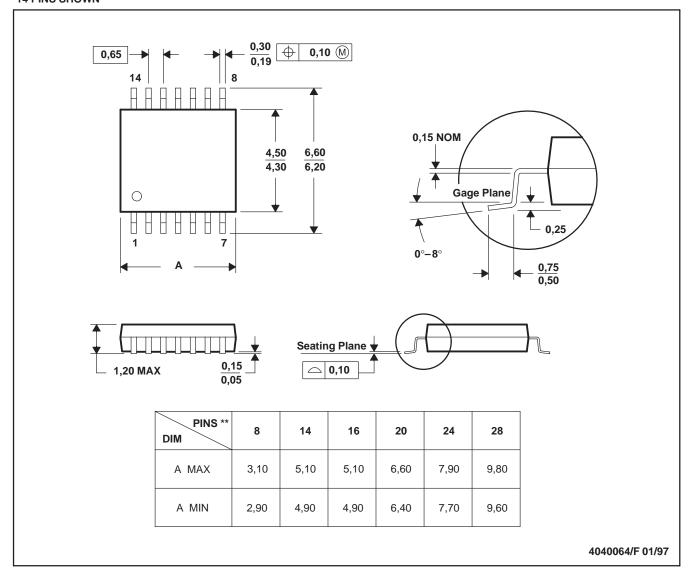
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



### PW (R-PDSO-G\*\*)

### 14 PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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